

PS7241-1B

4-PIN SOP 400 V BREAK DOWN VOLTAGE NORMALLY CLOSE TYPE 1-ch Optical Coupled MOS FET

DESCRIPTION

NEC

The PS7241-1B is a solid state relay containing GaAs LEDs on the light emitting side (input side) and normally close (N.C.) contact MOS FETs on the output side.

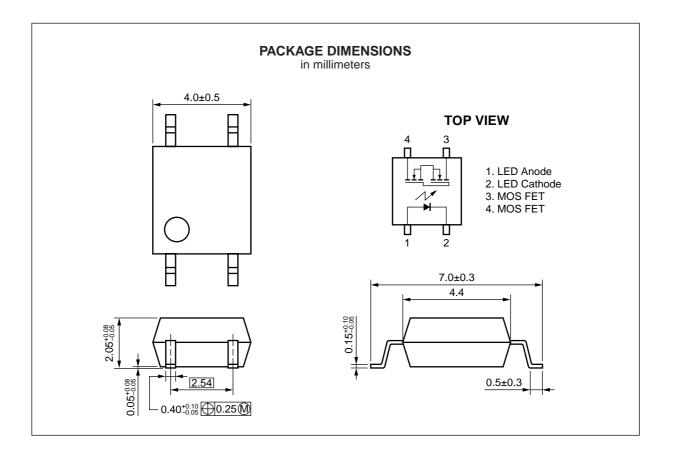
It is suitable for analog signal control because of its low offset and high linearity.

★ FEATURES

- Small and thin package (4-pin SOP, Height = 2.1 mm)
- 1 channel type (1 b output)
- Low LED operating current (IF = 2 mA)
- Designed for AC/DC switching line changer
- · Low offset voltage
- Ordering number of taping product: PS7241-1B-E3, E4, E5, F3, F4
- UL approved: File No. E72422 (S)
- BSI approved: No. 8241/8242
- CSA approved: No. CA 101391
- VDE approved: No. 121302 ÜG

APPLICATIONS

- Laptop PC, PDA
- Modem card
- Telephone, FAX
- Measurement equipment



***** ORDERING INFORMATION

Part Number	Package	Packing Style	Application Part Number*1
PS7241-1B	4-pin SOP	Magazine case 100 pcs	PS7241-1B
PS7241-1B-E3		Embossed Tape 900 pcs/reel	
PS7241-1B-E4			
PS7241-1B-E5		Embossed Tape 1 000 pcs/reel	
PS7241-1B-F3		Embossed Tape 3 500 pcs/reel	
PS7241-1B-F4			

*1 For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS (TA = 25 °C, unless otherwise specified)

Parameter		Symbol	Ratings	Unit	
Diode	Forward Current (DC)	lF	50	mA	
	Reverse Voltage	VR	5.0	V	
	Power Dissipation	PD	50	mW	
	Peak Forward Current ^{*1}	I FP	1	А	
MOS FET Break Down Voltage		VL	400	V	
	Continuous Load Current	١L	120	mA	
	Pulse Load Current ^{*2} (AC/DC Connection)	Ilp	240	mA	
	Power Dissipation	PD	300	mW	
Isolation Voltage ^{*3}		BV	1 500	Vr.m.s.	
Total Power Dissipation		Ρτ	350	mW	
Operating Ambient Temperature		TA	-40 to +80	°C	
Storage Temperature		Tstg	-40 to +100	°C	

*1 PW = 100 μ s, Duty Cycle = 1 %

*2 PW = 100 ms, 1 shot

*

*3 AC voltage for 1 minute at TA = 25 °C, RH = 60 % between input and output

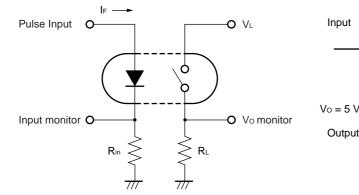
RECOMMENDED OPERATING CONDITIONS (TA = 25 °C)

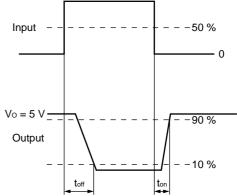
Parameter	Symbol	MIN.	TYP.	MAX.	Unit
LED Operating Current	lF	2	10	20	mA
LED Off Voltage	VF	0		0.5	V

ELECTRICAL CHARACTERISTICS (TA = 25 °C)

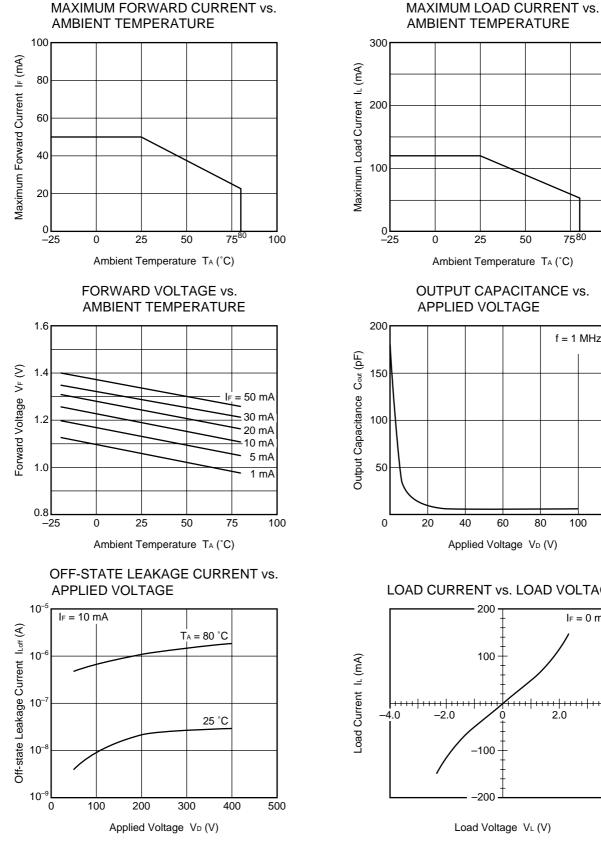
		Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
	Diode	Forward Voltage	VF	IF = 10 mA		1.2	1.4	V
		Reverse Current	IR	V _R = 5 V			5.0	μA
*	MOS FET	Off-state Leakage Current	Loff	IF = 10 mA, VD = 400 V		0.03	1.0	μA
		Output Capacitance	Cout	$I_F = 10 \text{ mA}, V_D = 0 \text{ V}, f = 1 \text{ MHz}$		170		pF
	Coupled	LED Off-state Current	Foff	I∟ = 120 mA			2.0	mA
		On-state Resistance	Ron1	IF = 0 mA, IL = 10 mA		24	35	Ω
*			Ron2	$I_F=0~mA,~I_L=120~mA,~t\leq 10~ms$		20	30	
		Turn-on Time [™]	ton	I_F = 10 mA, Vo = 5 V, PW \geq 10 ms		0.07	0.2	ms
		Turn-off Time ^{⁵1}	toff			0.8	2.0	
		Isolation Resistance	Ri-o	VI-O = 1.0 kVDC	10°			Ω
		Isolation Capacitance	CI-O	V = 0 V, f = 1 MHz		0.5		pF

★ *1 Test Circuit for Switching Time

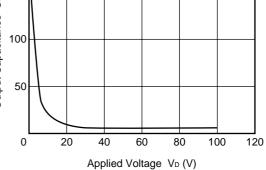


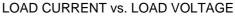


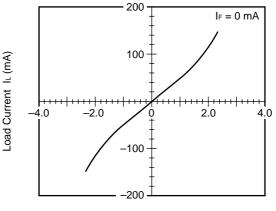
TYPICAL CHARACTERISTICS (TA = 25 °C, unless otherwise specified)



25 50 7580 100 Ambient Temperature T_A (°C) OUTPUT CAPACITANCE vs. APPLIED VOLTAGE f = 1 MHz





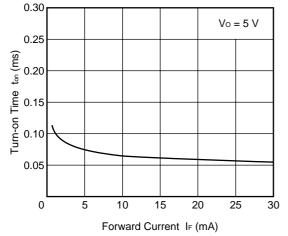


Load Voltage VL (V)

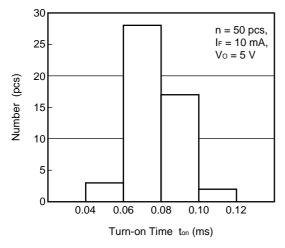
NORMALIZED ON-STATE RESISTANCE vs. AMBIENT TEMPERATURE 3.0 Ron Normalized to 1.0 at $T_A = 25$ °C, Normalized On-state Resistance 2.5 $I_F = 0 \text{ mA},$ I∟ = 10 mA 2.0 1.5 1.0 0.5 0.0∟ _25 0 25 50 75 100

Ambient Temperature T_A (°C)

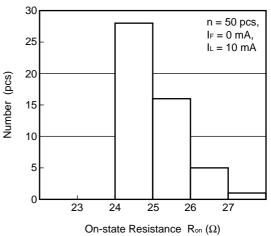




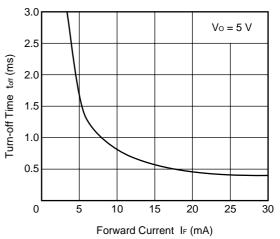




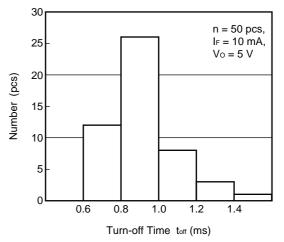
ON-STATE RESISTNACE DISTRIBUTION

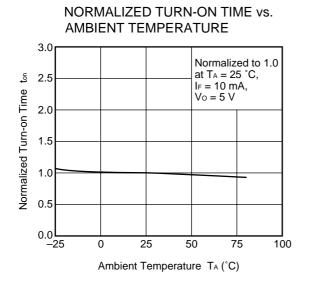


TURN-OFF TIME vs. FORWARD CURRENT

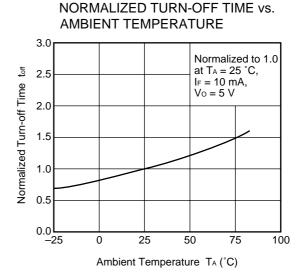


TURN-OFF TIME DISTRIBUTION

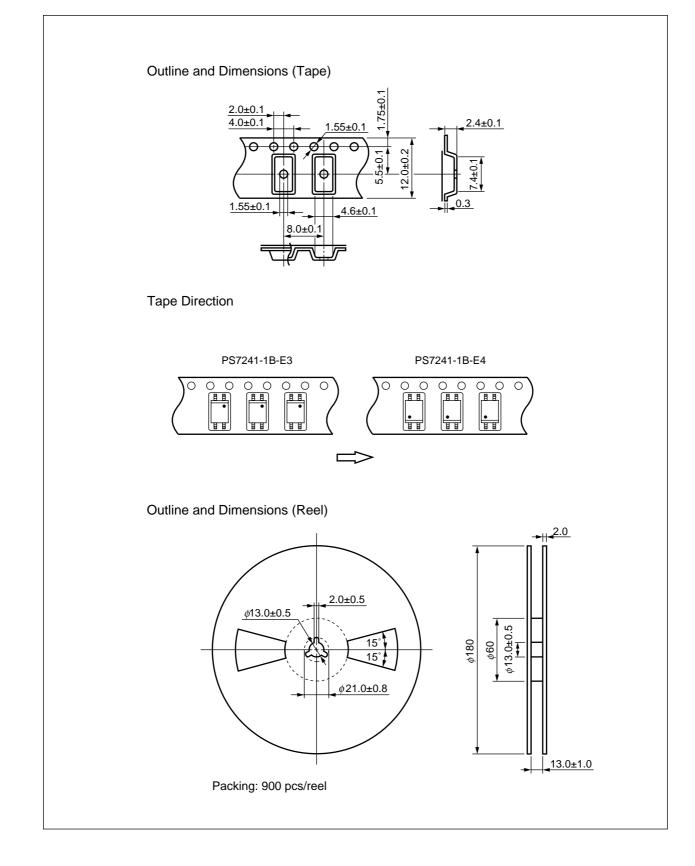


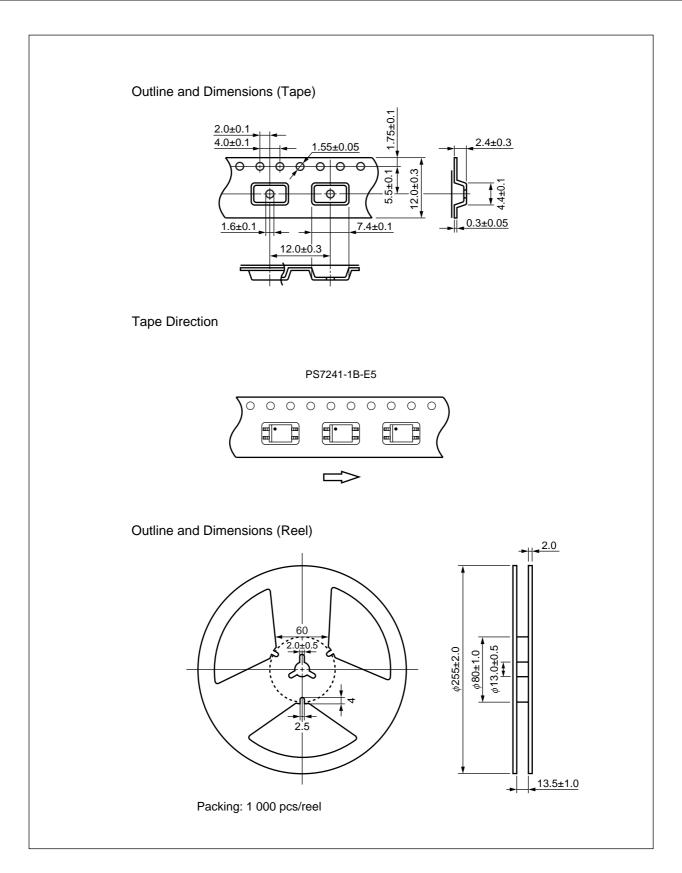


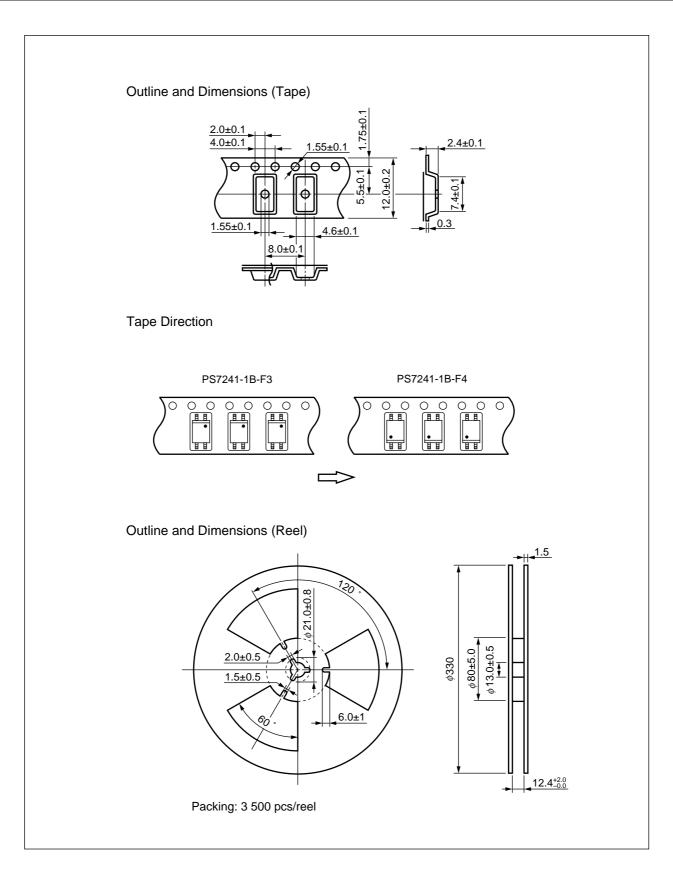
Remark The graphs indicate nominal characteristics.



★ TAPING SPECIFICATIONS (in millimeters)







***** RECOMMENDED SOLDERING CONDITIONS

(1) Infrared reflow soldering

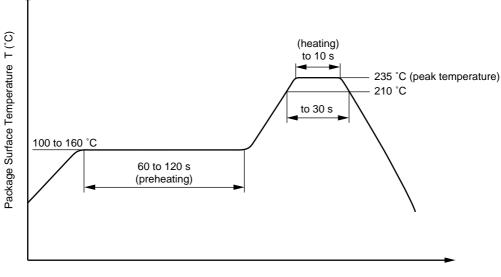
- Peak reflow temperature
 235 °C (package surface temperature)
- Time of temperature higher than 210 °C
- Number of reflows
- Flux

Two Rosin flux containing small amount of chlorine (The flux with a

maximum chlorine content of 0.2 Wt % is recommended.)

Recommended Temperature Profile of Infrared Reflow

30 seconds or less





(2) Dip soldering

Temperature 260 °C or below (molten solder temperature)

- Time
- 10 seconds or less
- Number of times One
- Flux

Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt % is recommended.)

(3) Cautions

• Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

CAUTION

Within this device there exists GaAs (Gallium Arsenide) material which is a harmful substance if ingested. Please do not under any circumstances break the hermetic seal.

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